

# **Integration and material budget studies of the CLIC\_ILD inner region**

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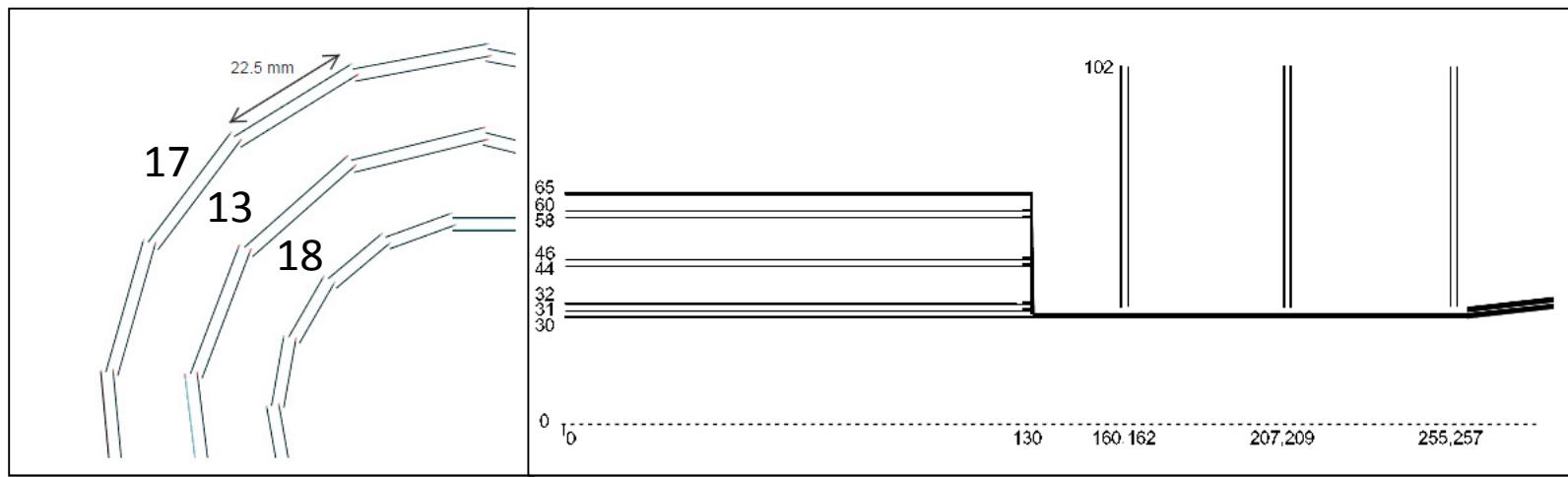
Fernando Duarte Ramos



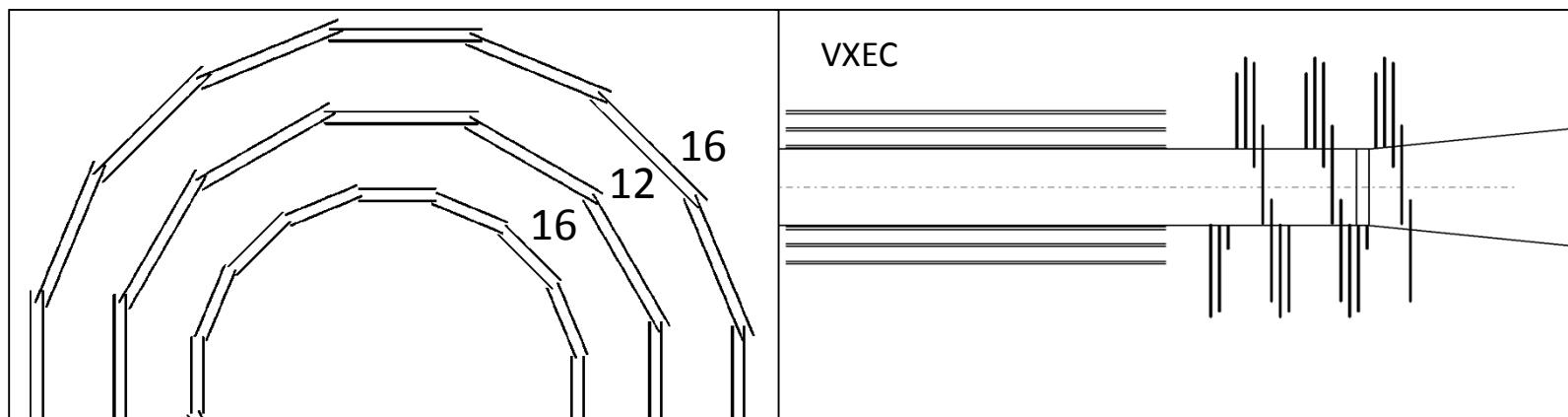
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# CLIC\_ILD Inner Region Layout – Detectors

Physics  
layout (CDR)



Engineering  
layout



- Vertex Barrel Detector:
- 3 double sided silicon pixel layers

- Vertex Endcaps:
- 3 double sided silicon pixel “pseudo-disks”
  - Helical and parallel distribution

## 0.CLIC\_ILD Layout

### 1.Cabling

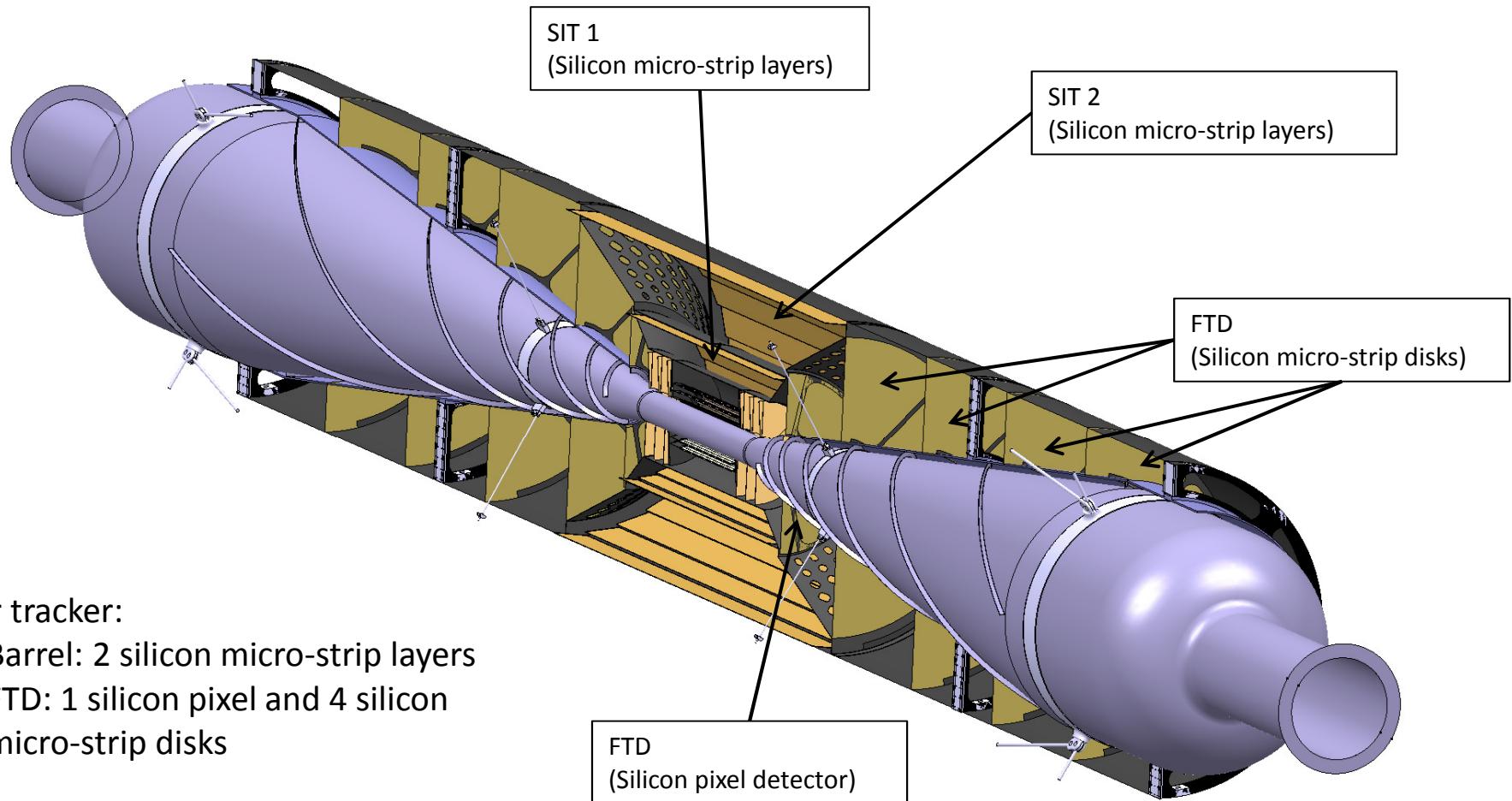
#### 1.1 Layout

### 2.Assembly process

- 2.1 Sub-assemblies
- 2.2 Full assembly

### 3.Material budget

# CLIC\_ILD Inner Region Layout – Detectors



## Inner tracker:

- Barrel: 2 silicon micro-strip layers
- FTD: 1 silicon pixel and 4 silicon micro-strip disks

## 0.CLIC\_ILD Layout

### 1.Cabling

#### 1.1 Layout

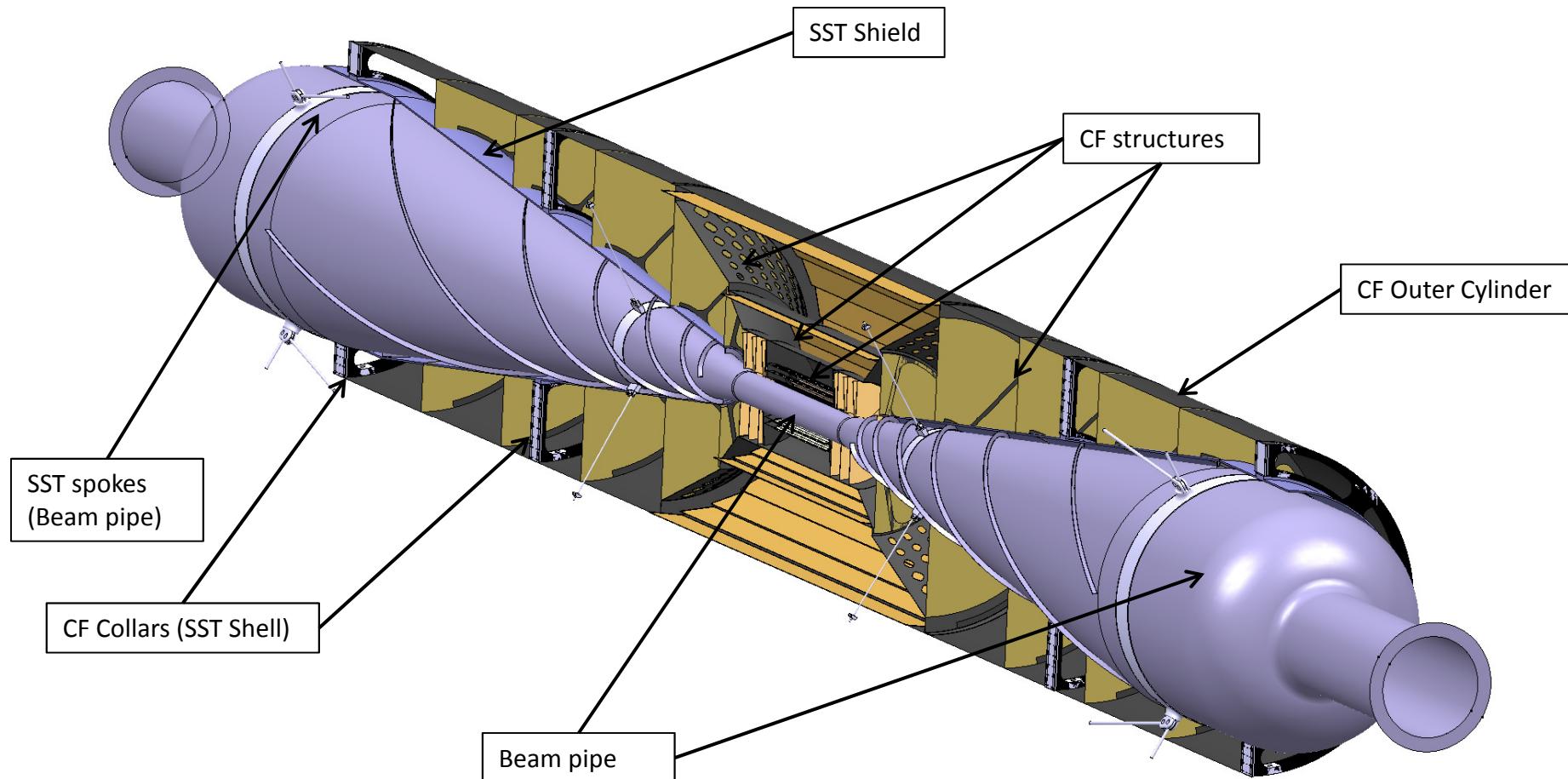
### 2.Assembly process

#### 2.1 Sub-assemblies

#### 2.2 Full assembly

### 3.Material budget

# CLIC\_ILD Inner Region Layout – Mechanical components



0.CЛИC\_ILD Layout

1.Cabling

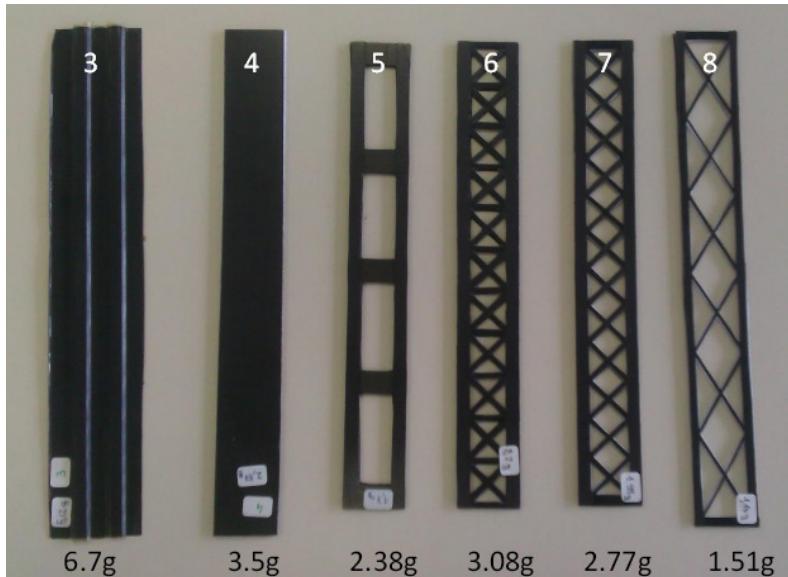
1.1 Layout

2.Assembly process

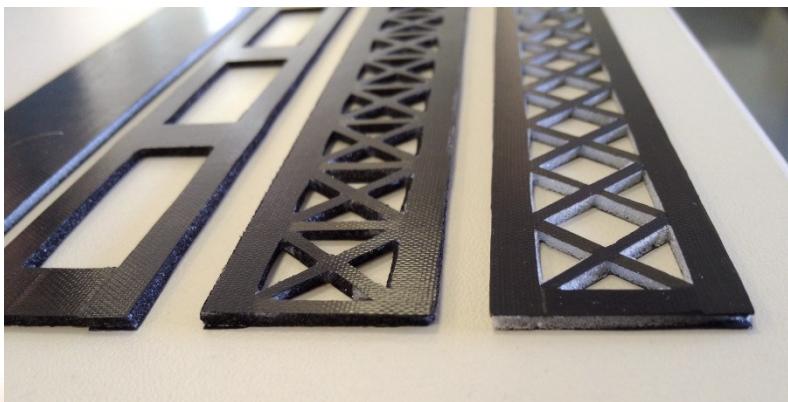
2.1 Sub-assemblies  
2.2 Full assembly

3.Material budget

# CF Structure – VXBD Staves



X/X₀					
0,156 %	0,134 %	0,091 %	0,118 %	0,106 %	0,058 %



0.CLIC\_ILD Layout

1.Cabling

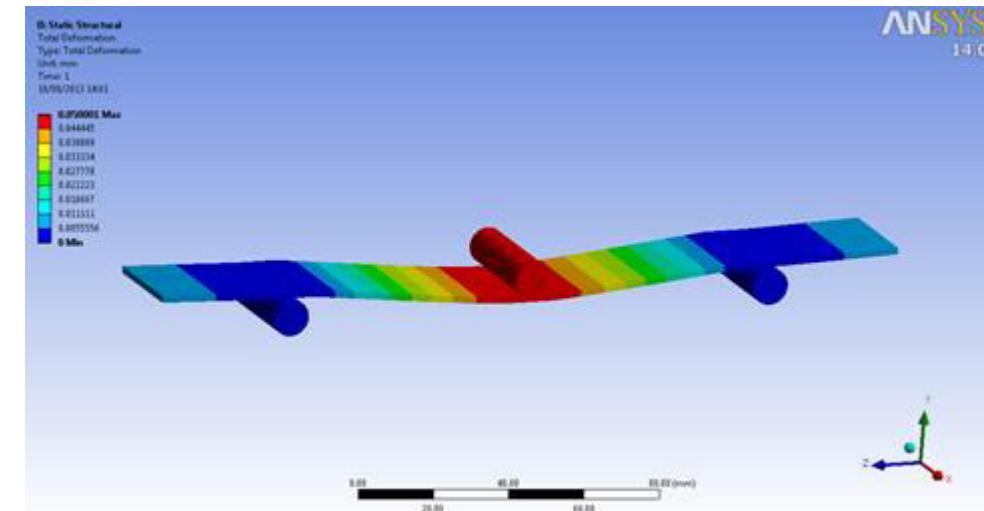
1.1 Layout

2.Assembly process

2.1 Sub-assemblies

2.2 Full assembly

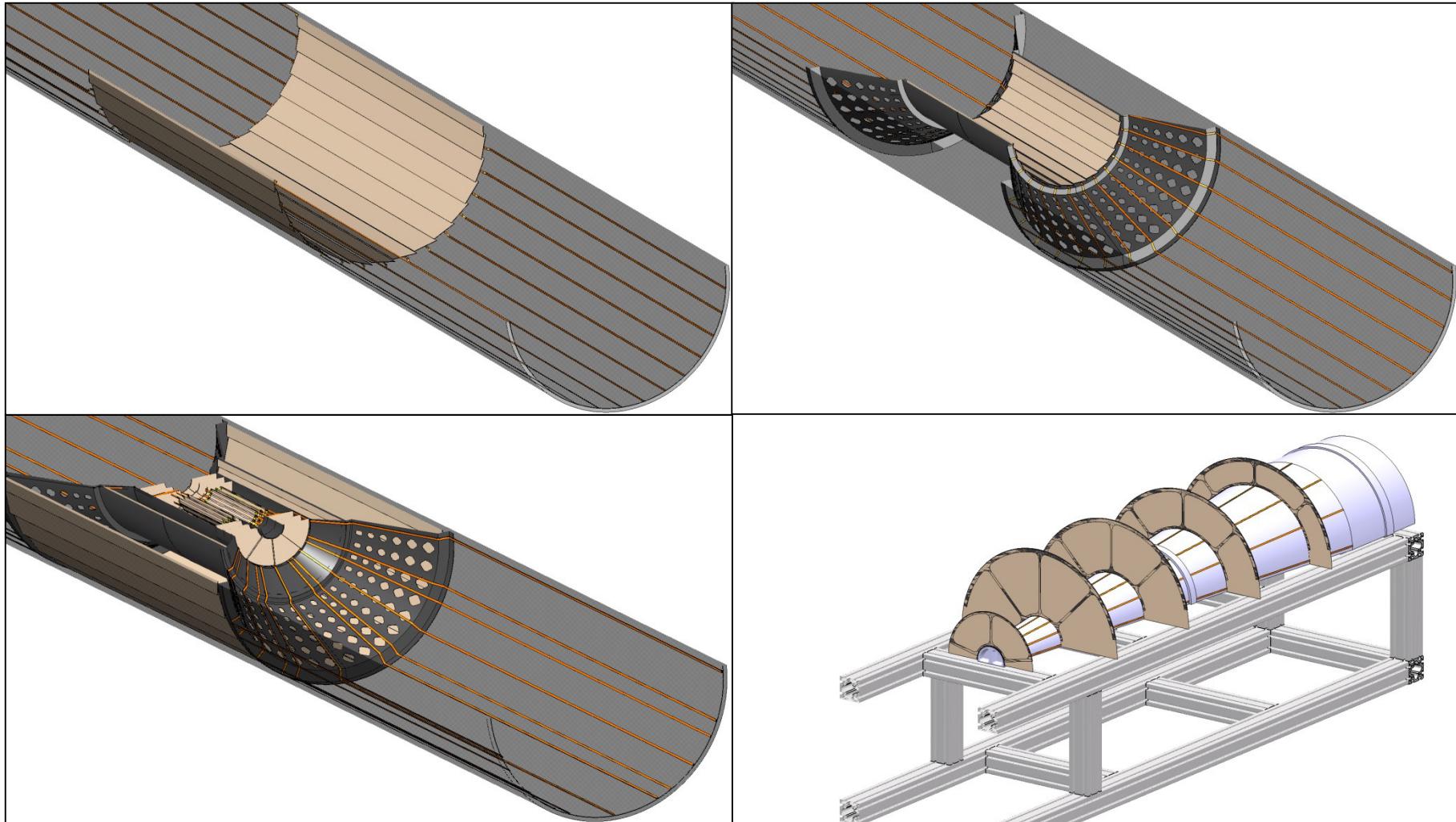
3.Material budget



PH-DT  
Detector Technologies

- Thanks to François-Xavier Nuiry

# Cabling layout



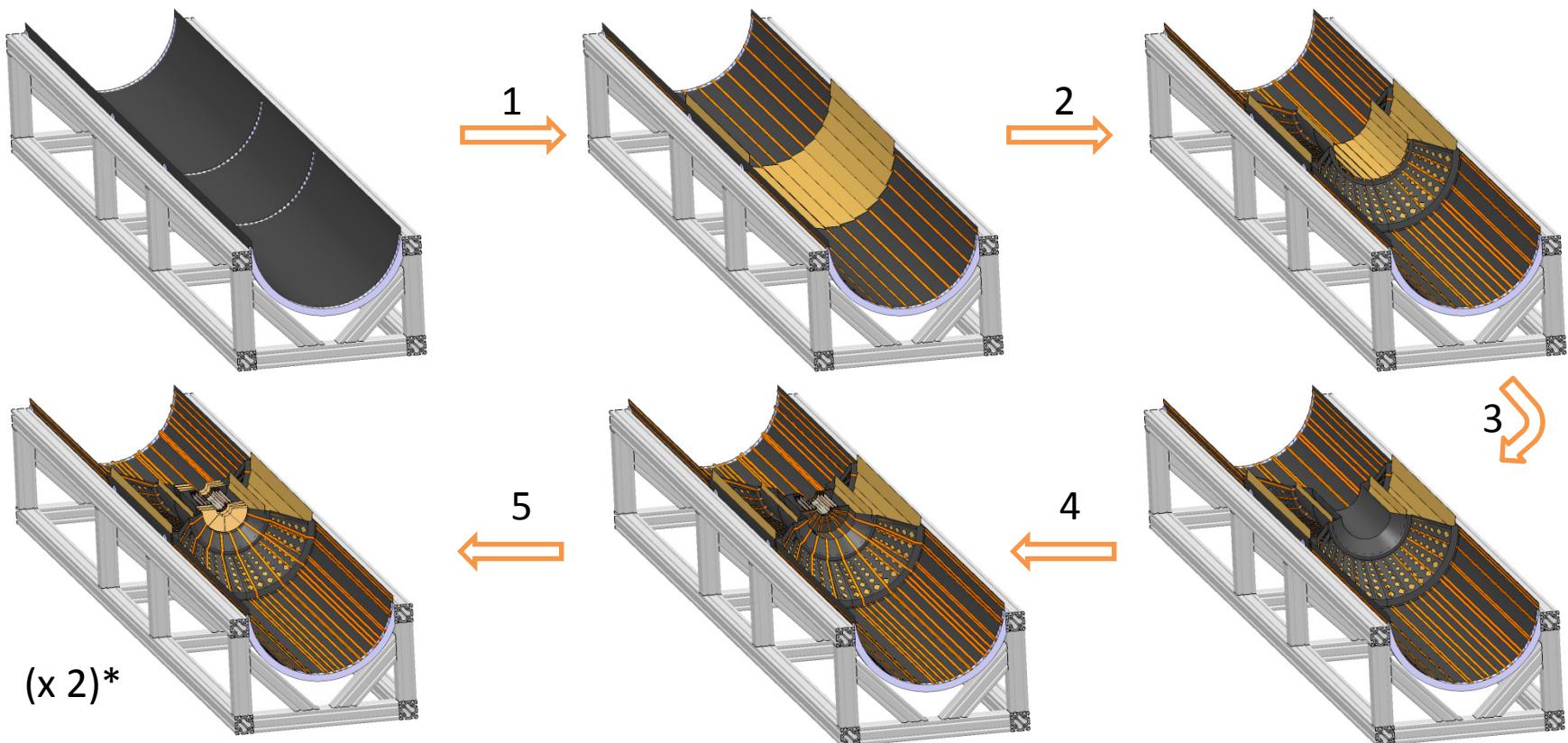
0.CЛИC\_ILD Layout

**1.Cabling**  
1.1 Layout

2.Assembly process  
2.1 Sub-assemblies  
2.2 Full assembly

3.Material budget

# Assembly process



1- Assembly of the SIT 2 and its cables

2- Assembly of the SIT 1 and its cables

3- Assembly of the CF support

4- Assembly of the VXBD and its cables

5- Assembly of the VSEC and its cables

\*the process is done two times (it is needed two half parts)

0.CЛИC\_ILD Layout

1.Cabling

1.1 Layout

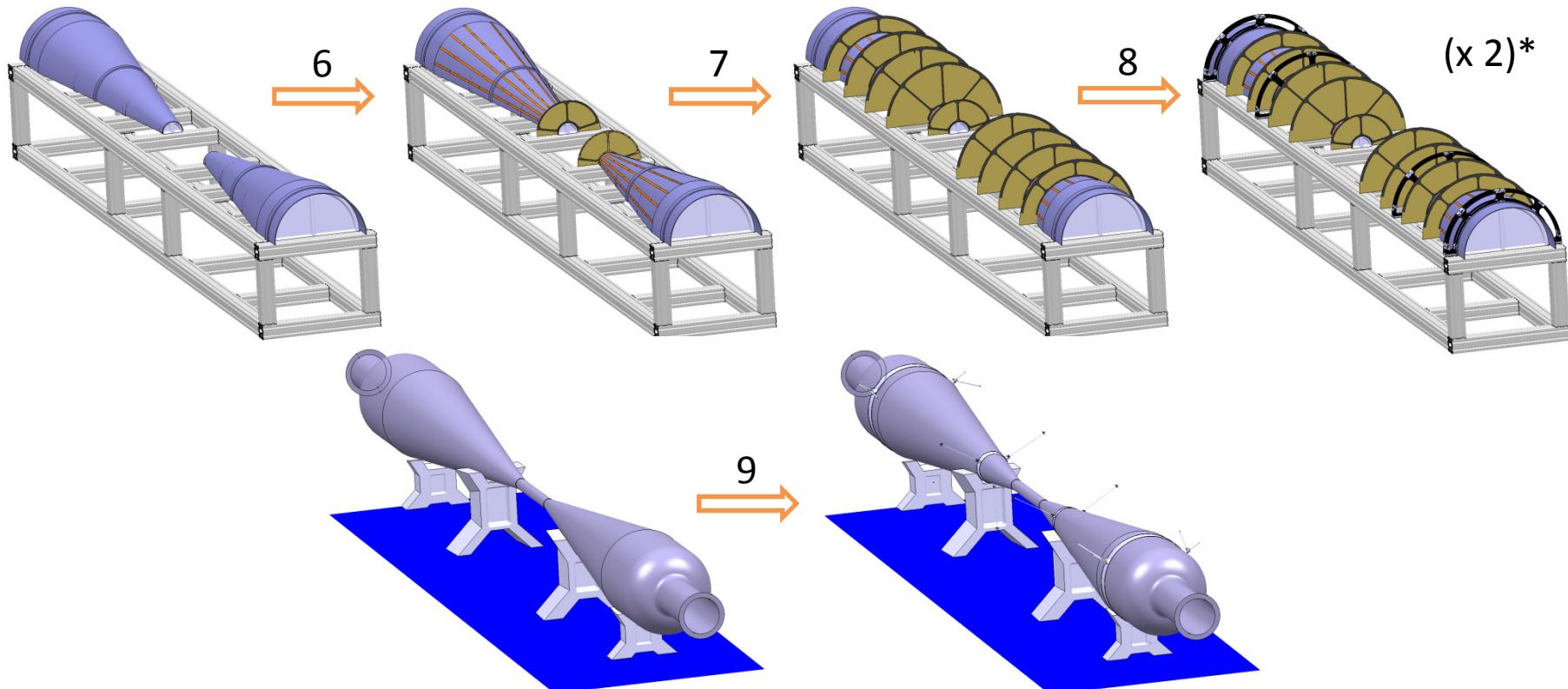
**2.Assembly process**

2.1 Sub-assemblies

2.2 Full assembly

3.Material budget

# Assembly process



6- Assembly of the FTD 1 and its cables

7- Assembly of the FTD 2-5 and its cables

8- Assembly of the carbon fiber supports

9- Assembly of the collars for the beam pipe

\*the process is done two times (it is needed two half parts)

0.CЛИC\_ILD Layout

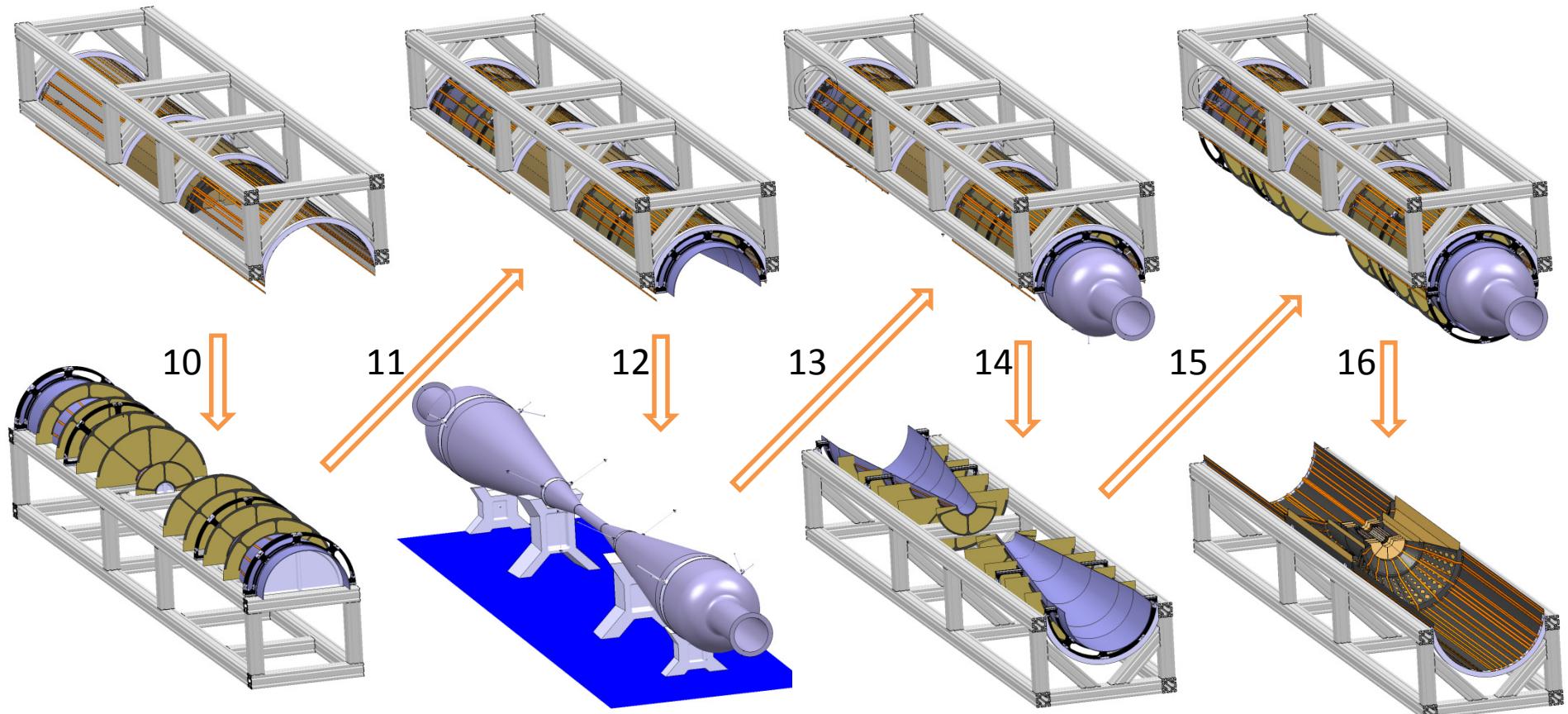
1.Cabling

1.1 Layout  
1.2 Simulation

**2.Assembly process**

**2.1 Sub-assemblies**  
**2.2 Full assembly**

3.Material budget



10- Assembly of one half of the carbon fiber cylinder with VXBD, VXE<sub>C</sub>, SIT 1 and SIT2 to one half of the FTD

11- Elevation of the assembly

12- Assembly to the beam pipe

13- Elevation of the assembly

14- Assembly to the other half of the FTD

15- Elevation of the assembly

16- Assembly with the other half part of the carbon fiber cylinder with its sensors

## 0.CLiC\_ILD Layout

### 1.Cabling

#### 1.1 Layout

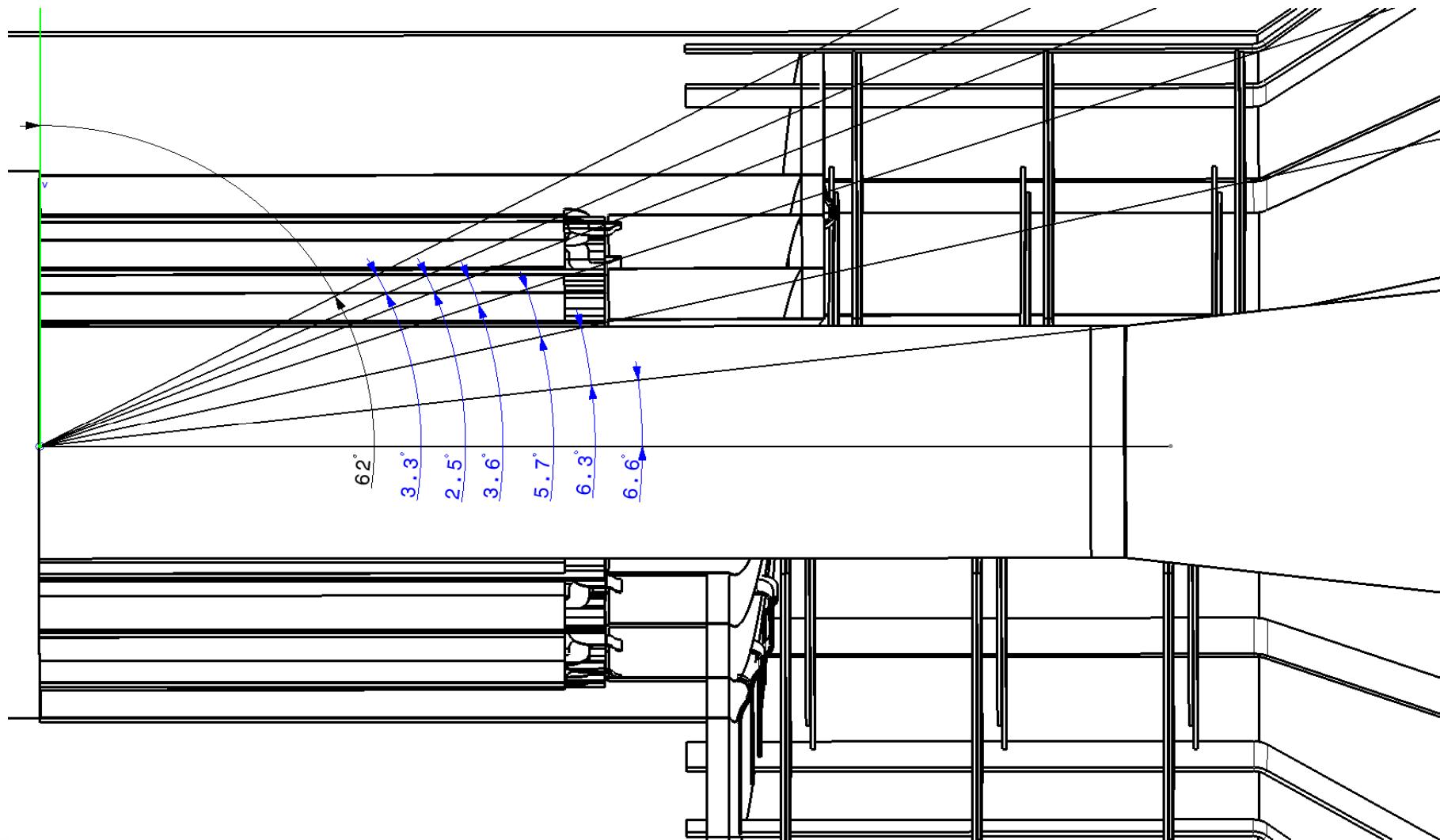
## 2.Assembly process

### 2.1 Sub-assemblies

### 2.2 Full assembly

## 3.Material budget

# Material Budget Calculations



0.CЛИC\_ILD Layout

1.Cabling

1.1 Layout

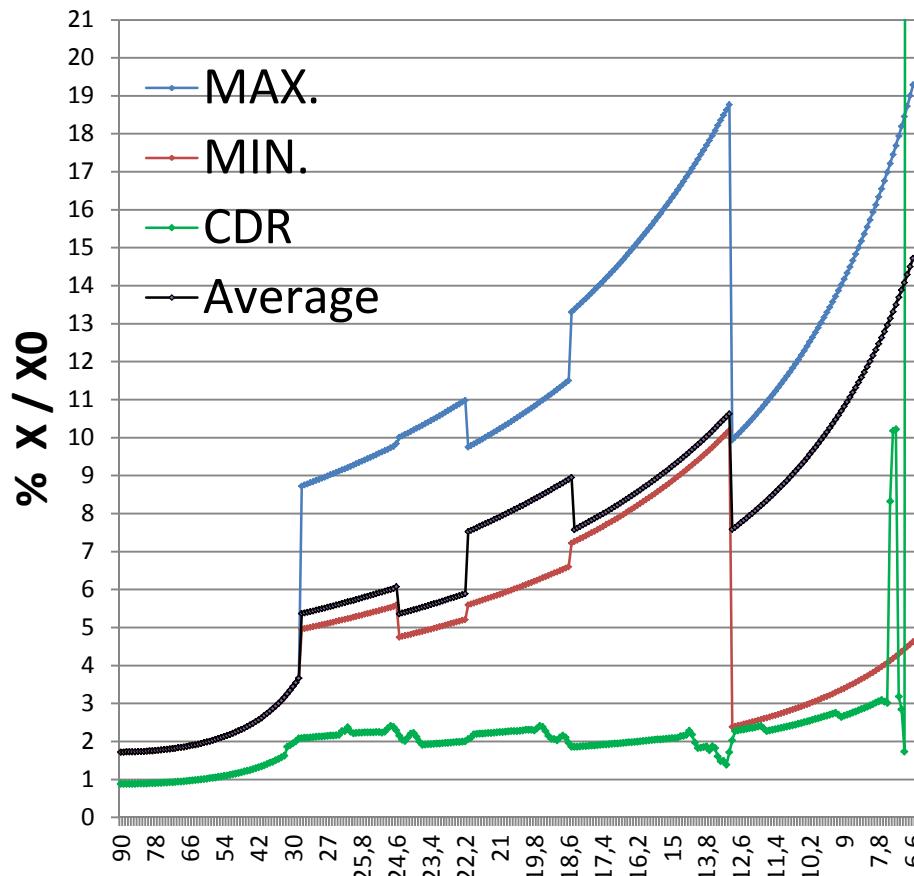
2.Assembly process

2.1 Sub-assemblies

2.2 Full assembly

3.Material budget

# Material Budget Calculations



Total material budget per VXBD double layer

Component	CDR	Calculation
$\theta=90^\circ$		$X/X_0$
Beam pipe (beryllium)	0,17%	0,17%
Double Layers 1-2	0,18%	0,40%
Double Layers 3-4	0,18%	0,40%
Double Layers 5-6	0,18%	0,40%
Support Shell	0,14%	0,35%
<b>Total</b>	<b>0,85%</b>	<b>1,72%</b>

- Observations:

$$\theta [{}^\circ]$$

- X axis **not** in scale

0.CЛИC\_ILD Layout

1.Cabling

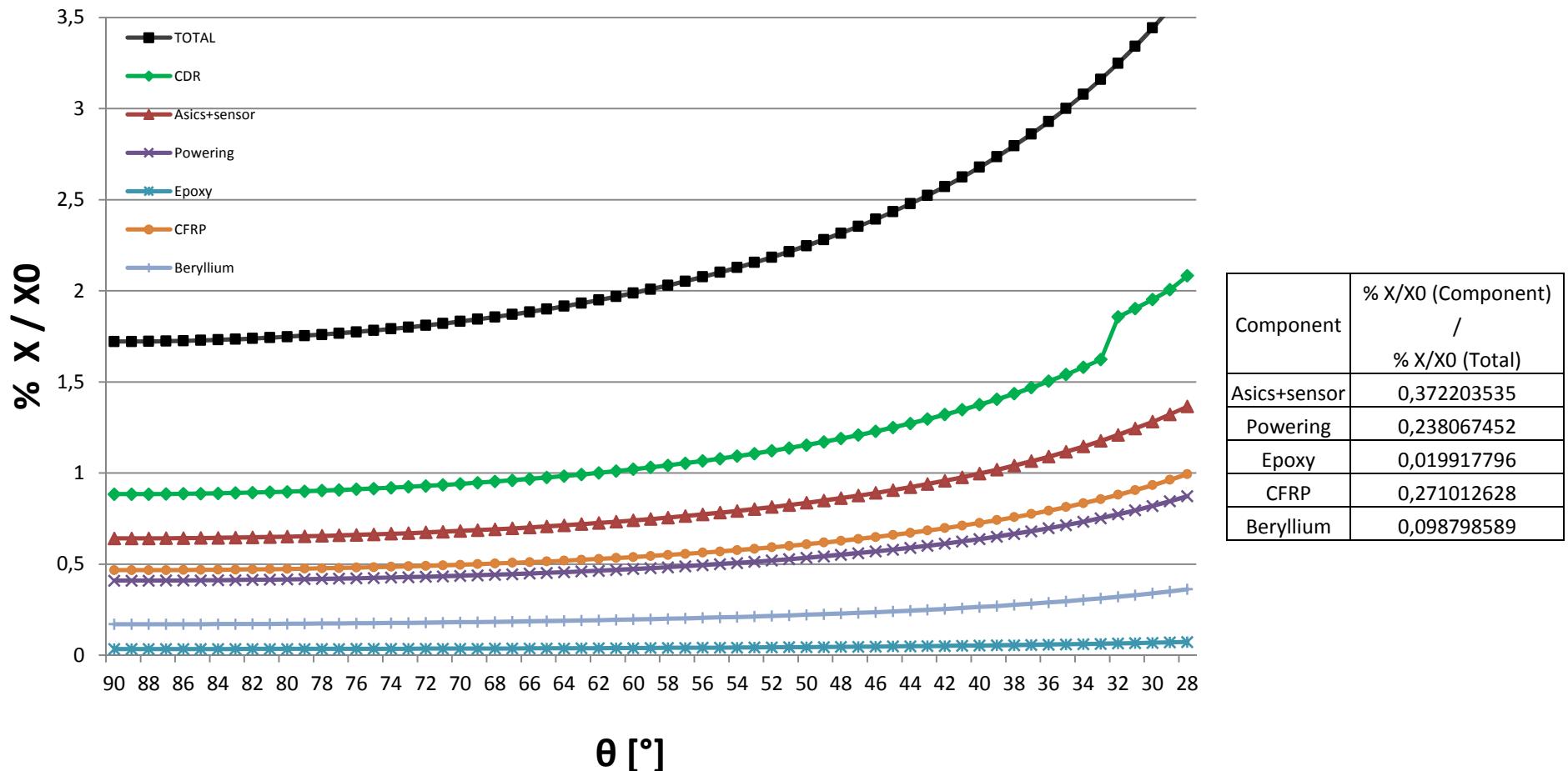
1.1 Layout

2.Assembly process

2.1 Sub-assemblies

3.Material budget

# Material Budget Calculations – 90°



0.CЛИC\_ILD Layout

1.Cabling  
1.1 Layout

2.Assembly process  
2.1 Sub-assemblies  
2.2 Full assembly

**3.Material budget**

# Summary

- Presentation of the Physics and Engineering layout.
- Staves manufactured prepared for testing and for verification of the simulations and the design.
- Possible layout for all the cables without interference with other parts.
- Feasible assembly process.
- Material budget comparisons between engineering and CDR model.